

OptiTIM Directions for Use

Shelf Life:

Shelf life for OptiTIM is 1 year from date of shipment at the storage conditions specified below.

Storage Conditions:

Recommended storage conditions are 0-35°C and relative humidity of 50% maximum. Store in original product packaging until ready for use.

Application Instructions:

- The application examples for applying OptiTIM outlined in this document are for a QSFP-DD module. The instructions also apply to other module form factors as well (SFP, SFP-DD, QSFP, CFX, CFP-2, etc).
- Not all heatsink designs are the same. For the best fit, maximum thermal performance, and mechanical reliability, Laird recommends submitting your heatsink design for review to determine optimal part size.
- For large volume application consult the factory for available automated processes.
- Parts will be provided on a strip between two backing liners as shown below in Figure 1.

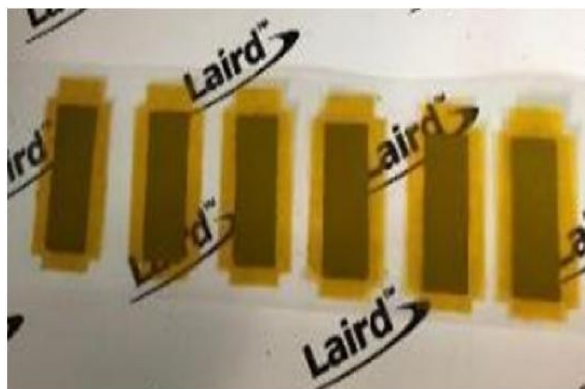


Figure #1: OptiTIM solution provided on backing liner

- Maintain a clean environment free of dust and other particulates. It is recommended for operators to use gloves when handling the product to prevent damage to the adhesive.
- Prior to application of the OptiTIM material, the surface of the heatsink should be cleaned with alcohol or acetone. Be sure the heatsink is completely dry before applying the OptiTIM material.
- Remove the OptiTIM pad from the backing liner and transfer to the heat sink with tweezers as shown below in Figure #2.

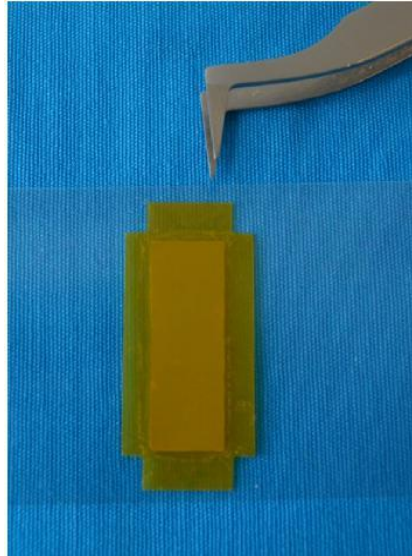


Figure #2: Remove the solution from the backing liner

- The adhesive side of OptiTIM pad should be applied on the heat sink surface aligning the gray area of the part over the pedestal as displayed in Figure #3.
- Align the gray material 1 to 2mm offset from the edge of the ramped section of the heatsink shown in Figure #3.
- If the solution is misplaced on the heat sink, you may need to remove the pad, clean the heatsink, and reapply a new OptiTIM pad.

A18043-00 OptiTIM Directions for Use 10-27-2021

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Offset the front edge of the gray material 1 to 2mm from ramp edge

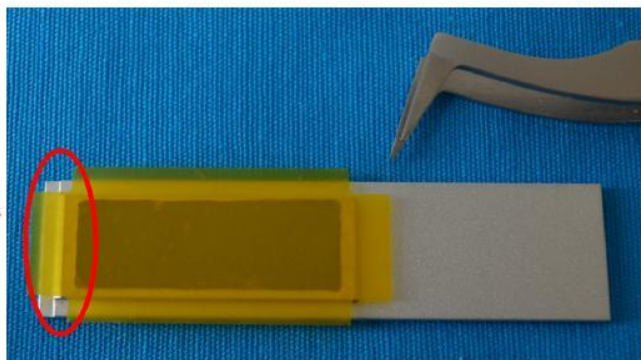


Figure #3: Apply solution to heat sink



Figure #4: Mating surfaces of solution and pedestal

- Carefully apply pressure on the adhesive portion (outer edges) of the OptiTIM to the pedestal and then tuck the outer edges down the vertical faces of the pedestal to ensure full adhesion.
- It is recommended to use a thin but dull instrument to assist in tucking the solution into the vertical/base corners as shown in Figure #5 and 6 for better adhesion.
- Start applying pressure to the adhesive on the pedestal first, then fold the outer edges over pedestal edges to vertical and ramped faces. Then tuck the solution into all the lower corners by using a dull instrument with right angle to apply pressure.



Figure #5

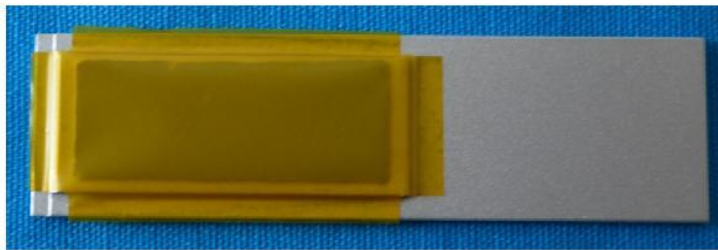


Figure #6